

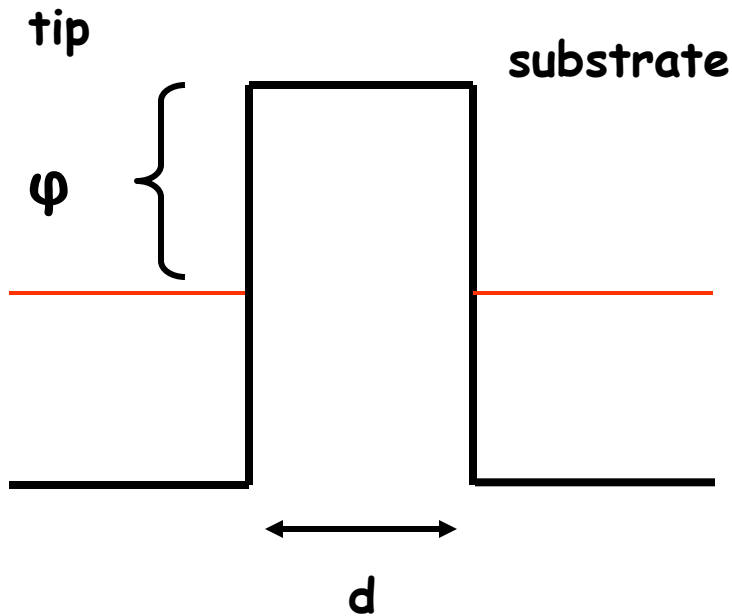
ME597/PHYS57000
Fall Semester 2009
Lecture 05

Some Topics in STM

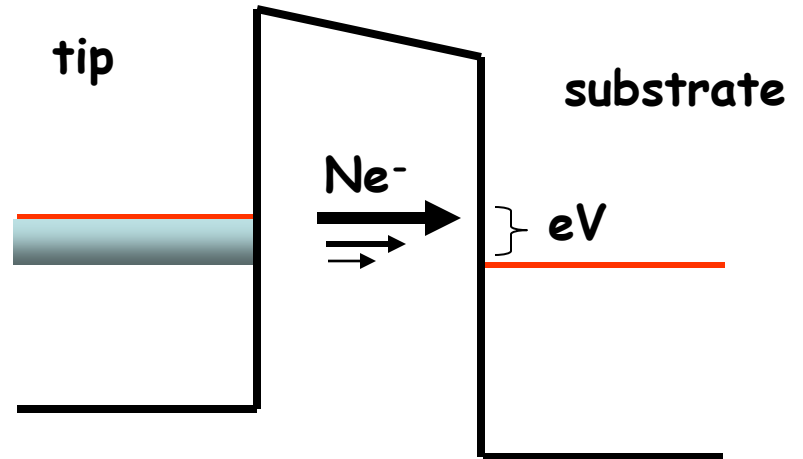
- Scanning Tunneling Spectroscopy (STS)
- Current Imaging Tunneling Spectroscopy (CITS)
- Apparent barrier height
- Force on the tip
- Atomic Corrugation
- Quantum Corrals

Scanning Tunneling Spectroscopy (STS)

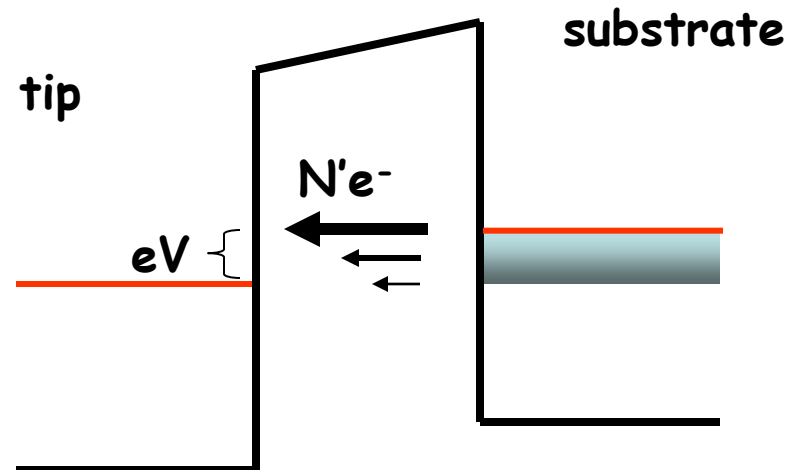
No bias voltage applied



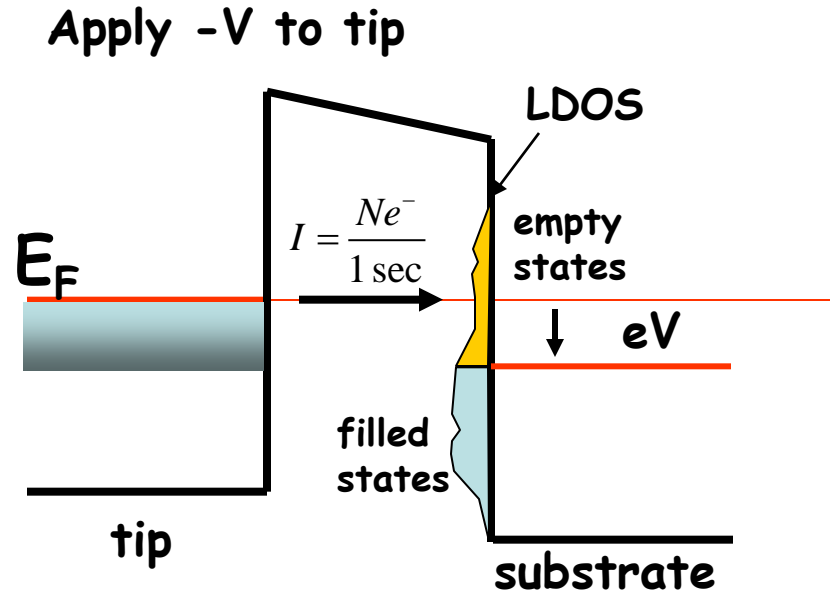
Apply $-V$ to tip



Apply $+V$ to tip



What determines number of electrons that flow per unit time for an applied V?



$$I = \frac{4\pi |e^-|}{\hbar} \int_{-\infty}^{\infty} [f(E_F + \varepsilon) - f(E_F - eV + \varepsilon)] \rho_{\text{tip}}(E_F + \varepsilon) \rho_{\text{substrate}}(E_F - eV + \varepsilon) T(\varepsilon, V) d\varepsilon$$

$f(E)$ is the Fermi-Dirac distribution function

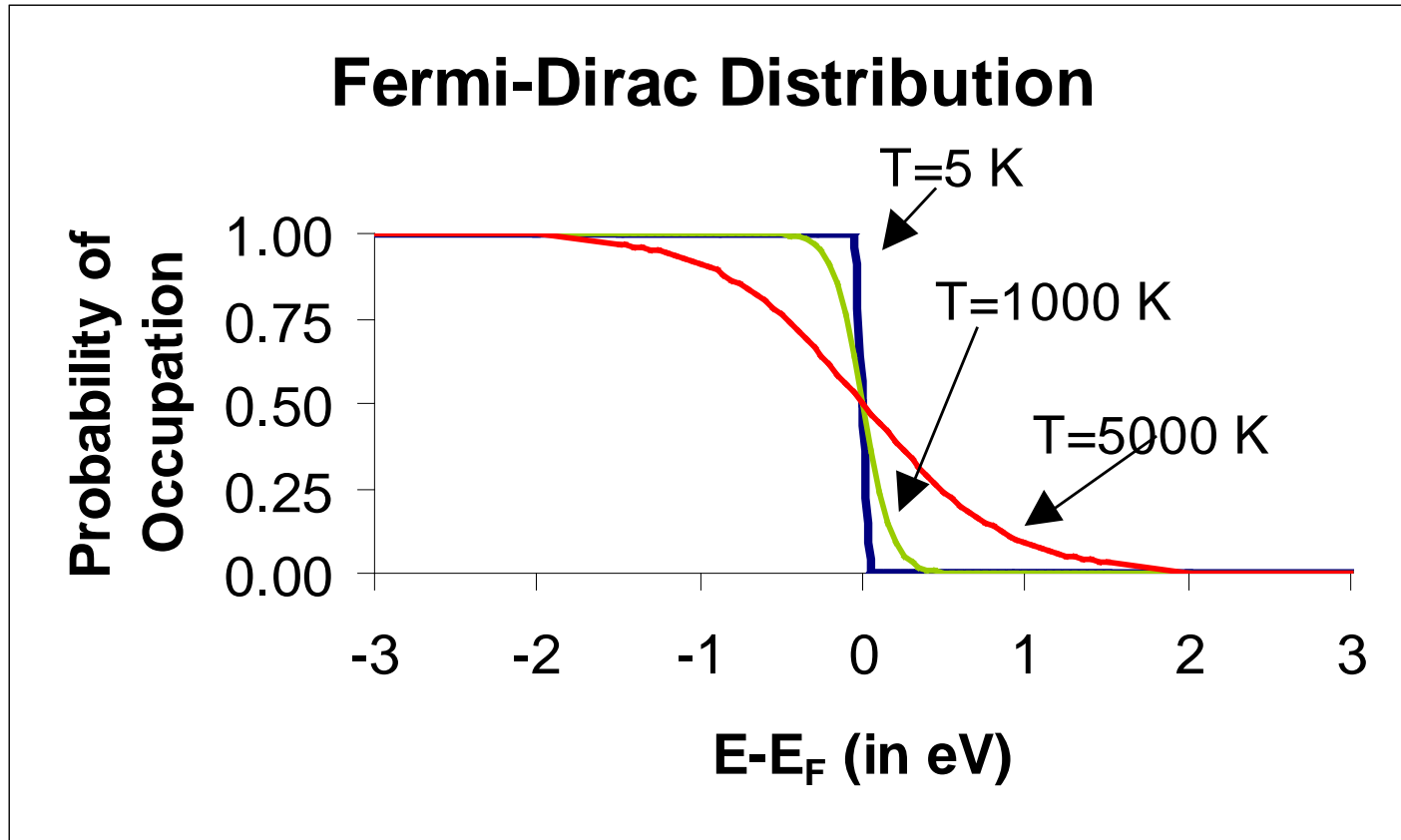
ρ_{tip} is the LDOS of tip

$\rho_{\text{substrate}}$ is the LDOS of substrate

$T(E, V)$ is the transmission probability at energy E for an applied voltage V

Fermi-Dirac distribution function

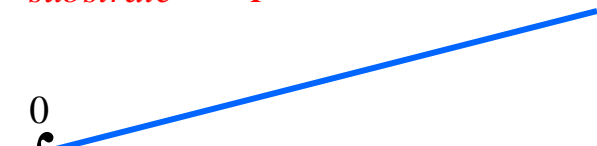
$$f(E) = \frac{1}{1 + e^{[(E-E_F)/k_B T]}}$$



A few reasonable assumptions:

- $k_B T$ at room temperature is 0.025 eV
- for voltage increments $\Delta V > \sim 2 k_B T/e$, $f(E)$ is well approximated by a step function
- assume tip DOS does not change appreciably with energy

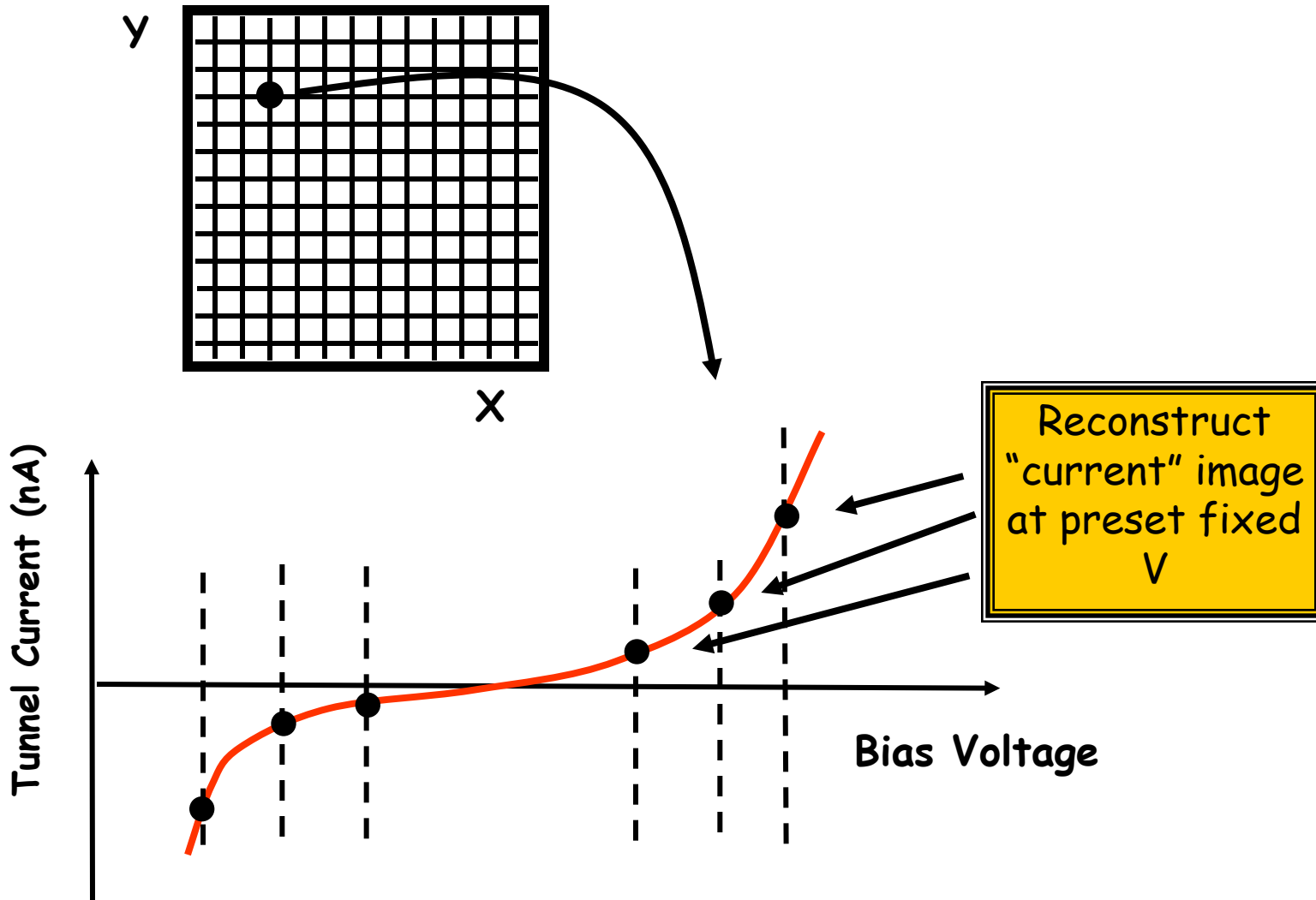
$$I \approx \frac{4\pi e}{\hbar} \rho_{tip}(E_F) \int_{-eV}^0 \rho_{substrate}(E_F - eV + \varepsilon) T(\varepsilon, V) d\varepsilon$$

$$\approx \frac{4\pi e}{\hbar} \rho_{tip}(E_F) \langle T \rangle \int_{-eV}^0 \rho_{substrate}(E_F - eV + \varepsilon) d\varepsilon$$


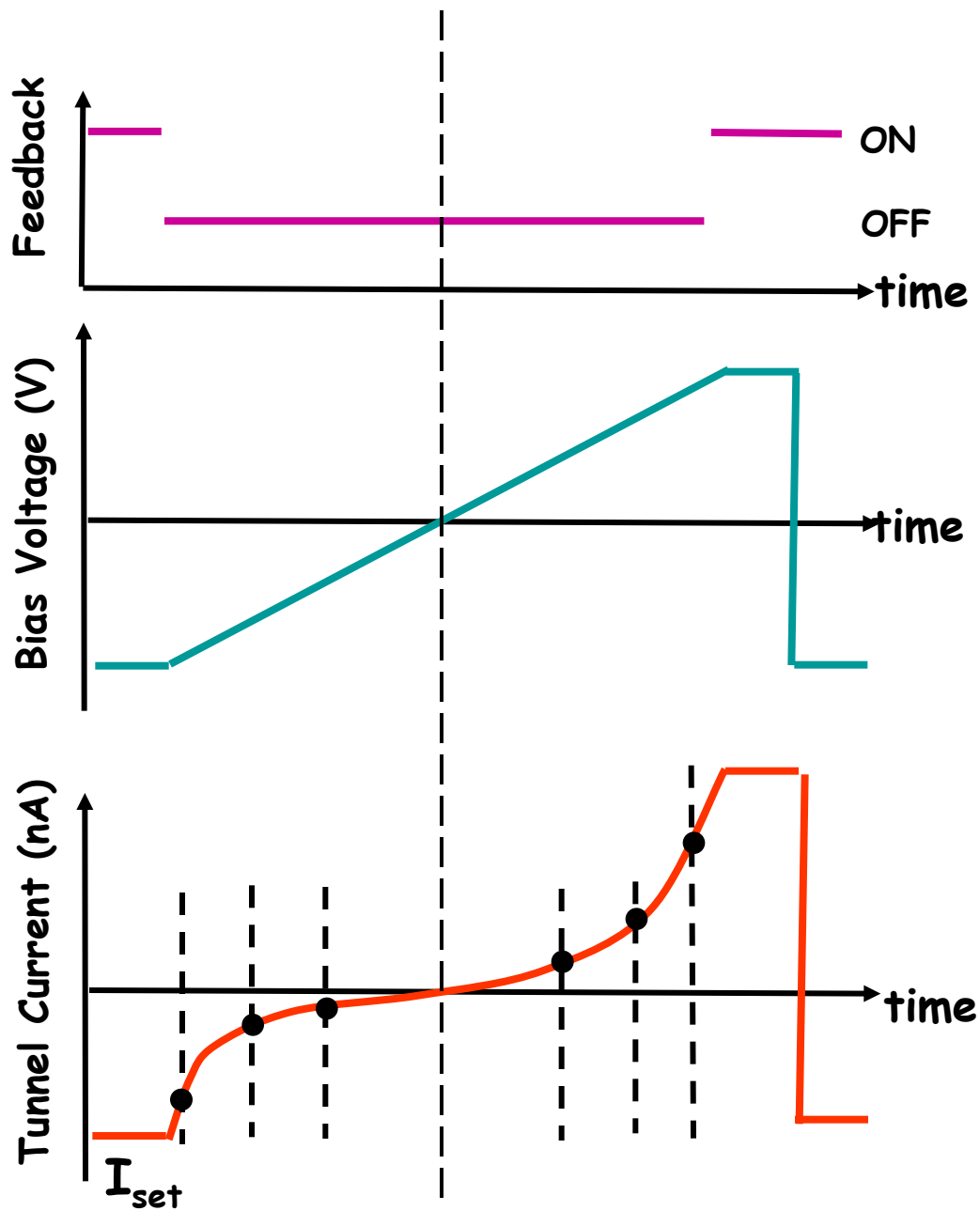
$$\left. \frac{\partial I}{\partial V} \right|_V \propto \text{constants} \times \rho_{substrate}(E_F - eV)$$

Current Imaging Tunneling Spectroscopy (CITS)

Measure $I(V)$ at each point:

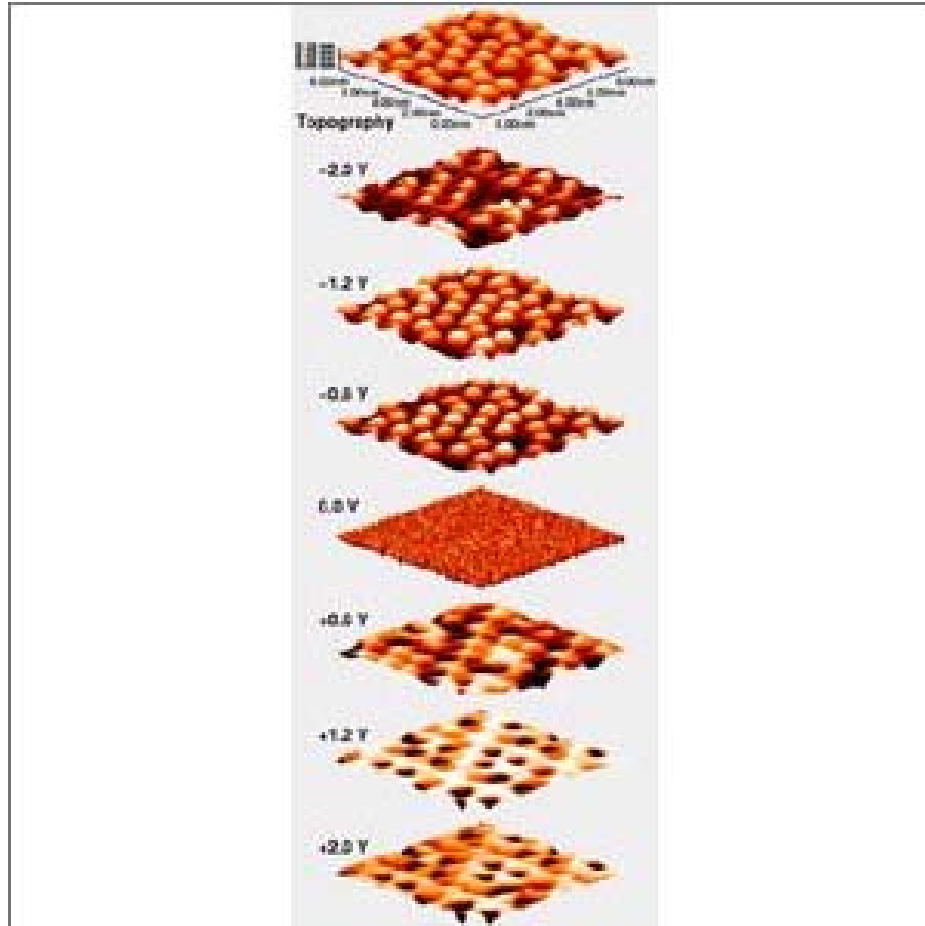


Making it work



Example

Current Imaging (CITS) on a perfect Si(111)7x7 Surface



Key Idea: Acquire an (x,y) image at different voltages. Useful to visualize filled and unfilled states at each (x,y) point

Current Imaging Tunneling Spectroscopy on Si(111)7x7 at room temperature. The topographic image is shown at the top ($I(t) = 0.35$ nA, $U_{\text{gap}} = 1.73$ V), followed by several CITS images ranging from -2.0 V to +2.0 V. Spectroscopy data have been taken at every point of the frame for these images.

Measuring the apparent tunnel barrier height

Recall for a constant tip bias $I = I_o e^{-2\alpha z}$ where $\alpha = \sqrt{\frac{2m\phi_{barrier}}{\hbar^2}}$

$$\ln(I) = \ln(I_o) - 2 \frac{\sqrt{2m \phi_{barrier} \text{ (in J)}}}{\hbar} z \text{ (in m)}$$

change units: $2 \frac{\sqrt{2m}}{\hbar} \left[\sqrt{1.6 \times 10^{-19} \phi_{barrier} \text{ (in eV)}} \right] \left[1 \times 10^{-10} z \text{ (in \AA)} \right]$

the constant is now $2 \frac{\sqrt{2m}}{\hbar} \left[\sqrt{1.6 \times 10^{-19}} \right] \left[1 \times 10^{-10} \right] = 1.029$

$$\ln(I) = \ln(I_o) - 1.029 \times \sqrt{\phi_{barrier} \text{ (in eV)}} \times z \text{ (in \AA)}$$

$$\left[\frac{\partial [\ln(I)]}{\partial z \text{ (in \AA)}} \right]^2 = (1.029)^2 \times \phi_{barrier} \text{ (in eV)}$$

$$\therefore \phi_{barrier} \text{ (in eV)} = \frac{1}{(1.029)^2} \times \left[\frac{\partial [\ln(I)]}{\partial z \text{ (in \AA)}} \right]^2 = 0.94 \times \left[\frac{\partial [\ln(I)]}{\partial z \text{ (in \AA)}} \right]^2$$

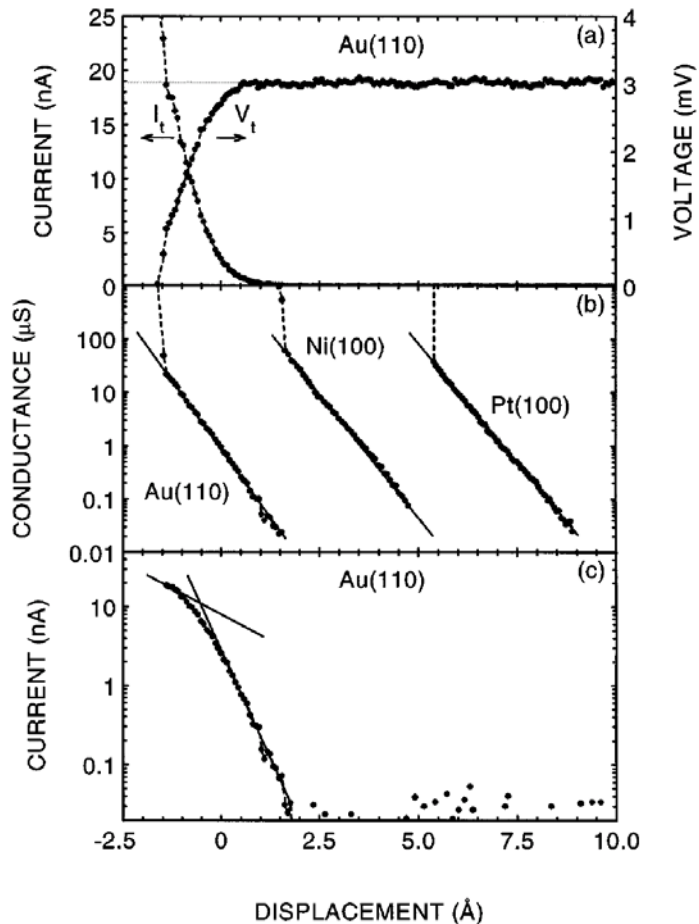
Apparent Barrier Height in Scanning Tunneling Microscopy Revisited

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(Received 3 November 1995)



$$\begin{aligned} \phi_{\text{barrier}} [Au(110)] &= 4.7 \pm 1.0 \text{ eV} \\ \phi_{\text{barrier}} [Ni(100)] &= 4.5 \pm 0.7 \text{ eV} \\ \phi_{\text{barrier}} [Pt(100)] &= 3.4 \pm 0.8 \text{ eV} \end{aligned}$$

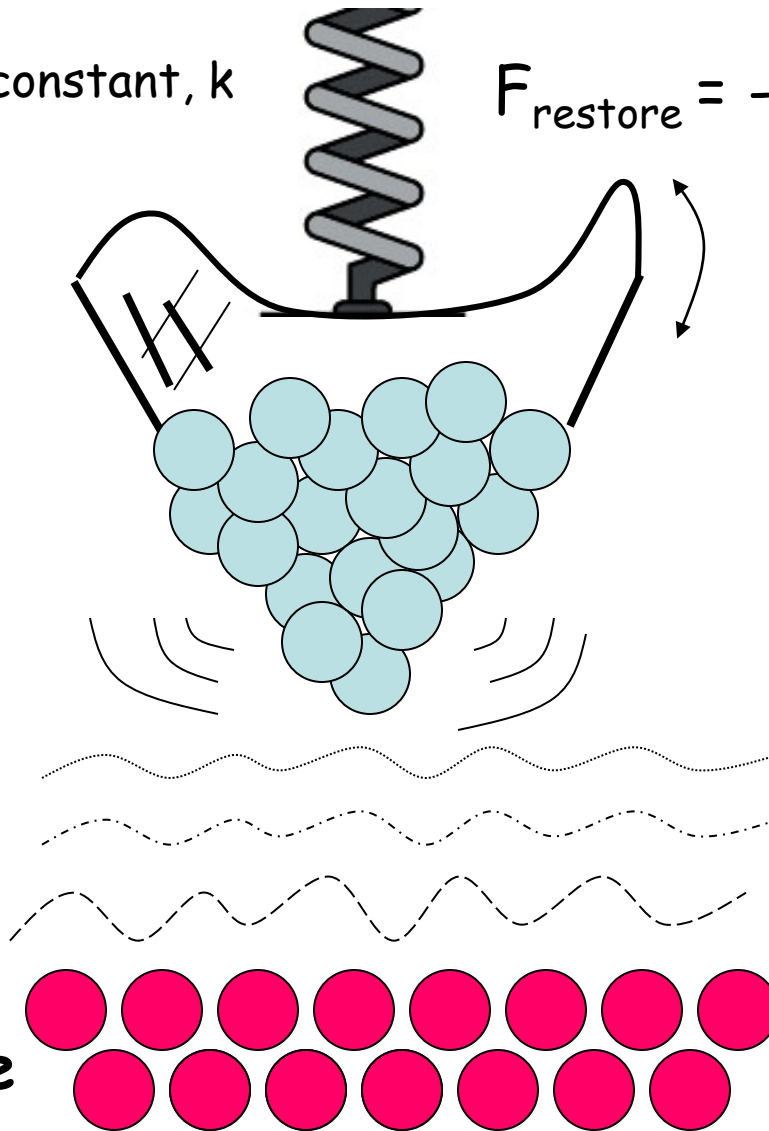
The Force on the Tip Atom?

spring constant, k $F_{\text{restore}} = -kz$

tip

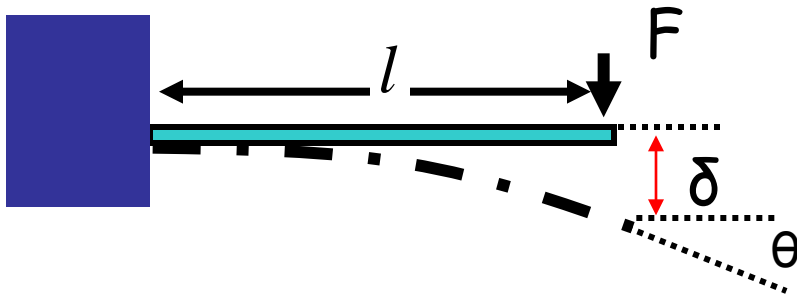
collective tip-
substrate
interaction
+ atom-
atom
interactions

substrate



How to measure?

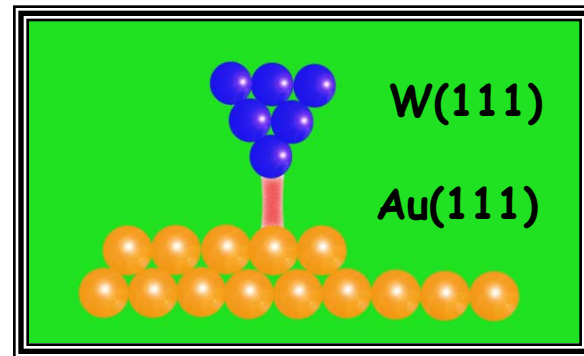
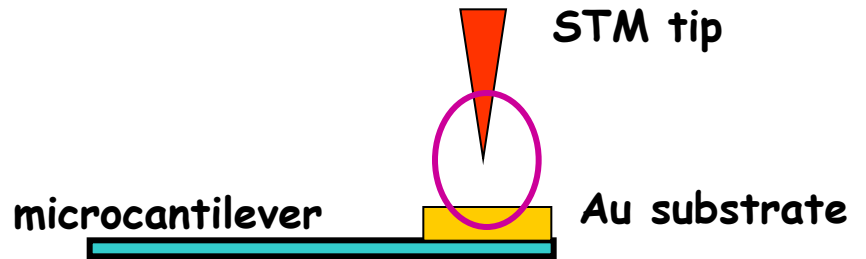
Cantilever Physics - static model



$$\delta = \frac{Fl^3}{3EI} \quad \theta = \frac{Fl^2}{2EI}$$

$$k = \frac{3EI}{l^3} = \frac{Ewt^3}{4l^3}$$

$$F = k\delta = \frac{2}{3}k l\theta$$



Adhesion Interaction between Atomically Defined Tip and Sample

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(Received 24 November 1997)

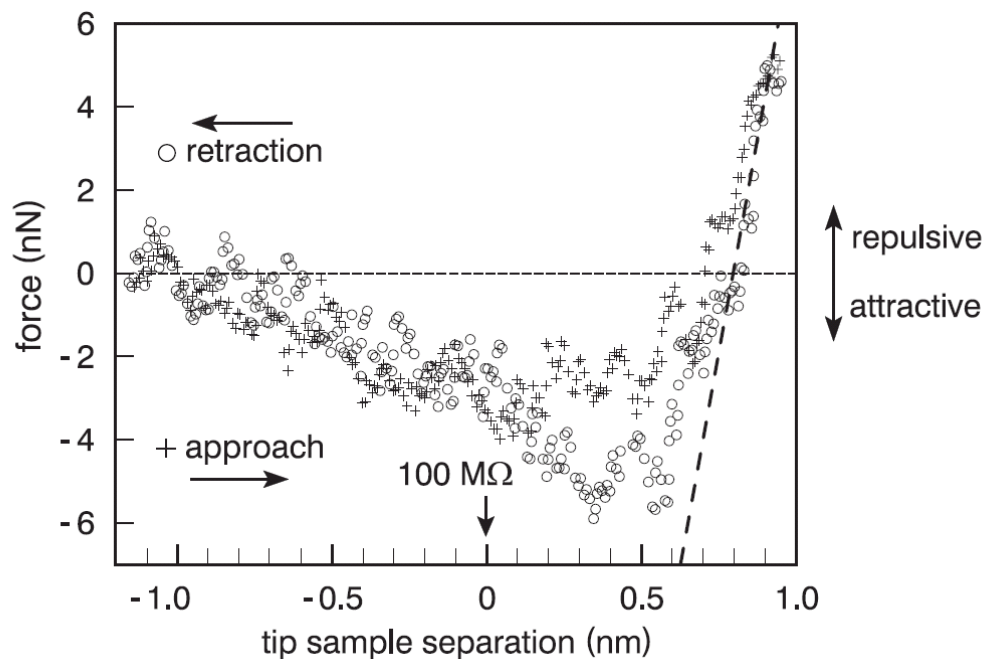


FIG. 3. Force versus tip-sample separation measured on a flat terrace using a W-trimer tip (tip-sample separation is defined as the relative motion of the tip with respect to the substrate using a tunnel resistance of $100\text{ M}\Omega$ as the reference point). Note the hysteresis of 7 eV between the approach and retraction curve, indicating that dissipative processes take place in the range of the adhesion maximum. Also note that no spontaneous jump to contact followed by the formation of an adhesion neck occurs. The attractive interaction has a length scale of 1 nm , 1 order of magnitude larger than expected from universal scaling laws. The repulsive branch of the force curve is essentially linear (corresponding to a contact stiffness of $40 \pm 20\text{ N/m}$, indicated by the dashed line) and reversible. Surprisingly, the tip-sample junction can support a repulsive load of at least 5 nN corresponding to a contact pressure of 25 GPa . The compounded errors in determining the force scale correspond to $\pm 35\%$; the compounded errors in the tip-sample separation s are $\pm 20\%$.

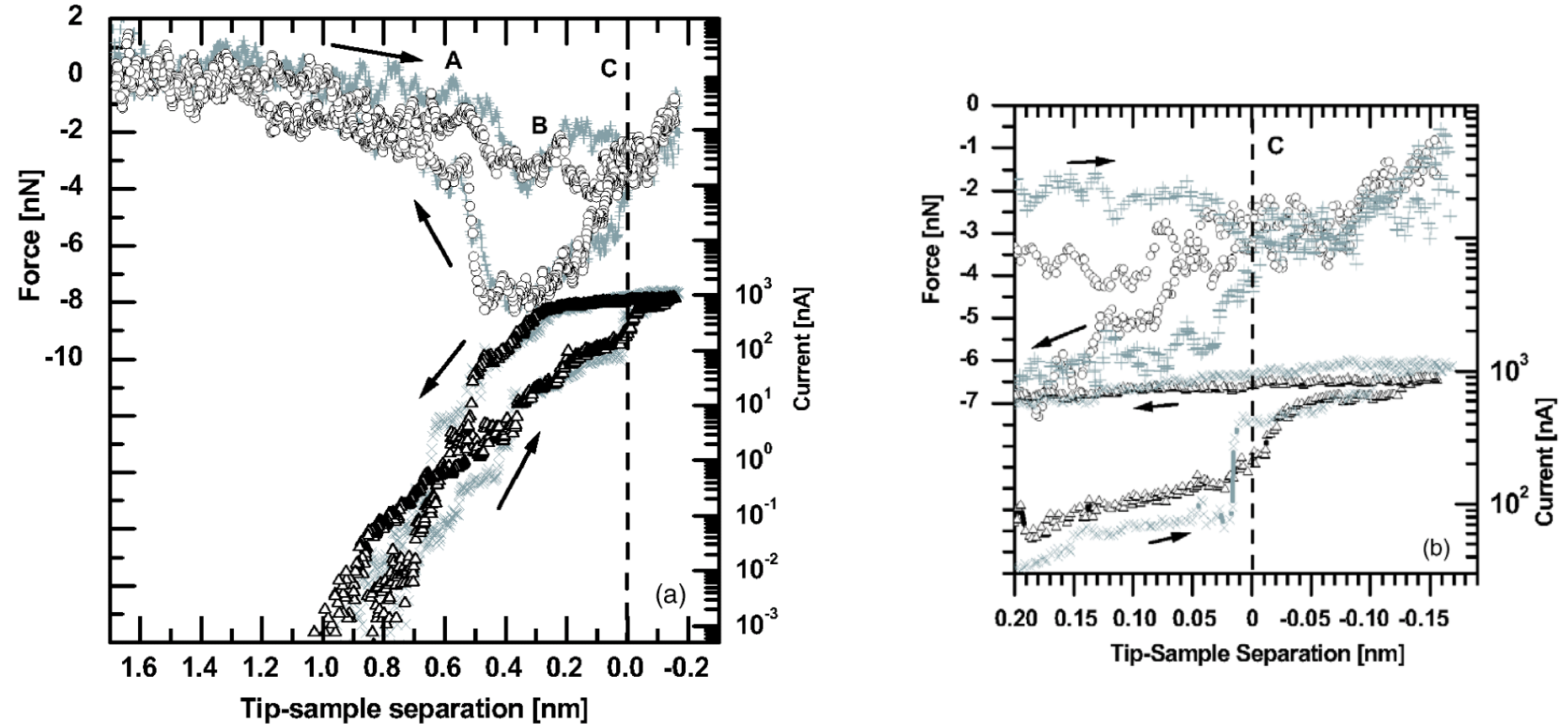
$$\frac{V_{bias}}{I} = 100\text{ M}\Omega$$

From tunneling to point contact: Correlation between forces and current

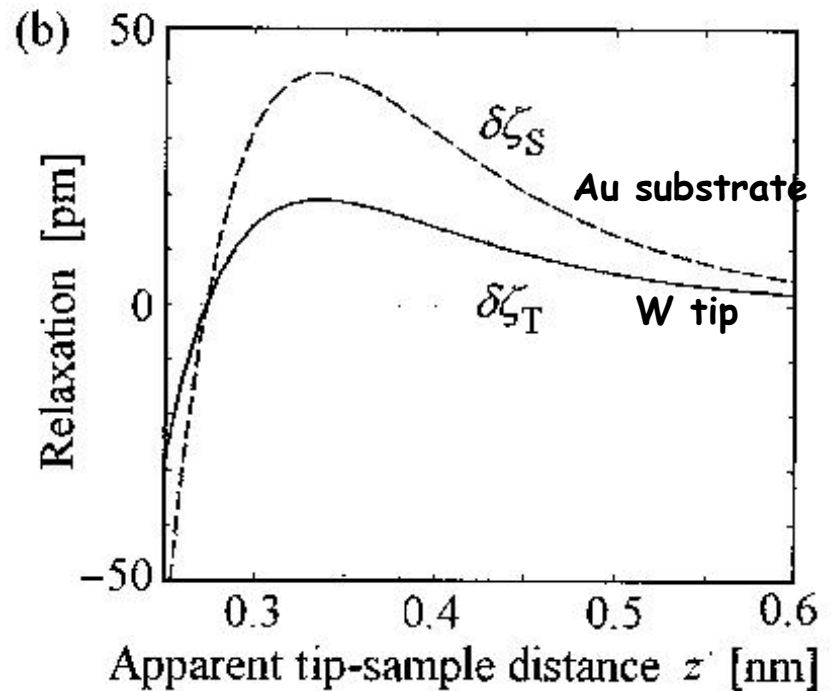
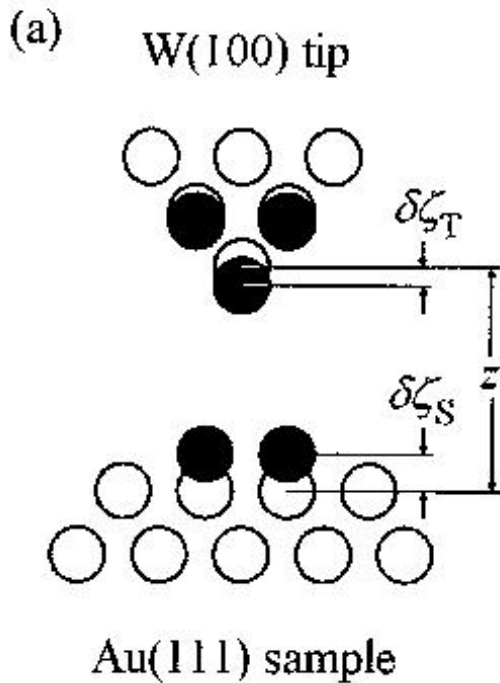
Yan Sun, Henrik Mortensen, Sacha Schär, Anne-Sophie Lucier, Yoichi Miyahara, and Peter Grütter
Department of Physics, McGill University, 3600 University Street, Montreal, Quebec, H3A 2T8, Canada

Werner Hofer

Surface Science Research Centre and the Department of Physics, University of Liverpool, United Kingdom
(Received 7 February 2005; published 25 May 2005)



Junction Stability Nanomechanical Effects



Atomic Corrugation - How High is an Atom?

PHYSICAL REVIEW B

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Prediction of bias-voltage-dependent corrugation reversal for STM images of bcc (110) surfaces: W(110), Ta(110), and Fe(110)

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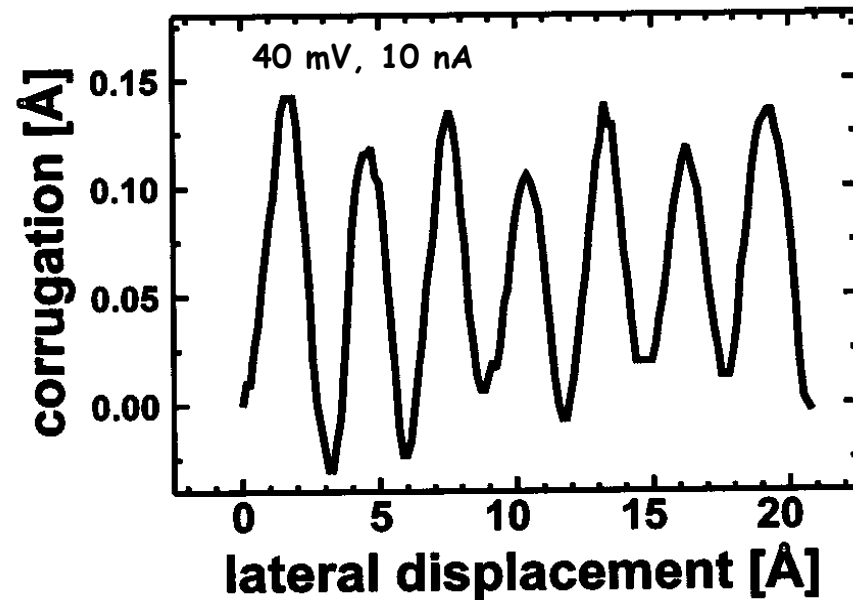
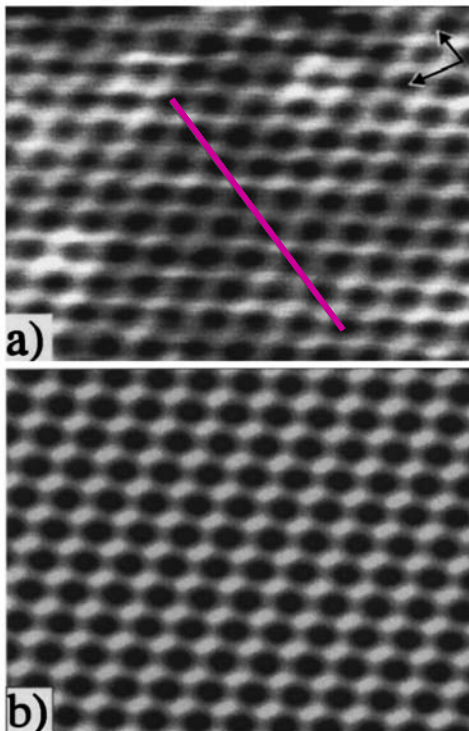
S. Blügel*

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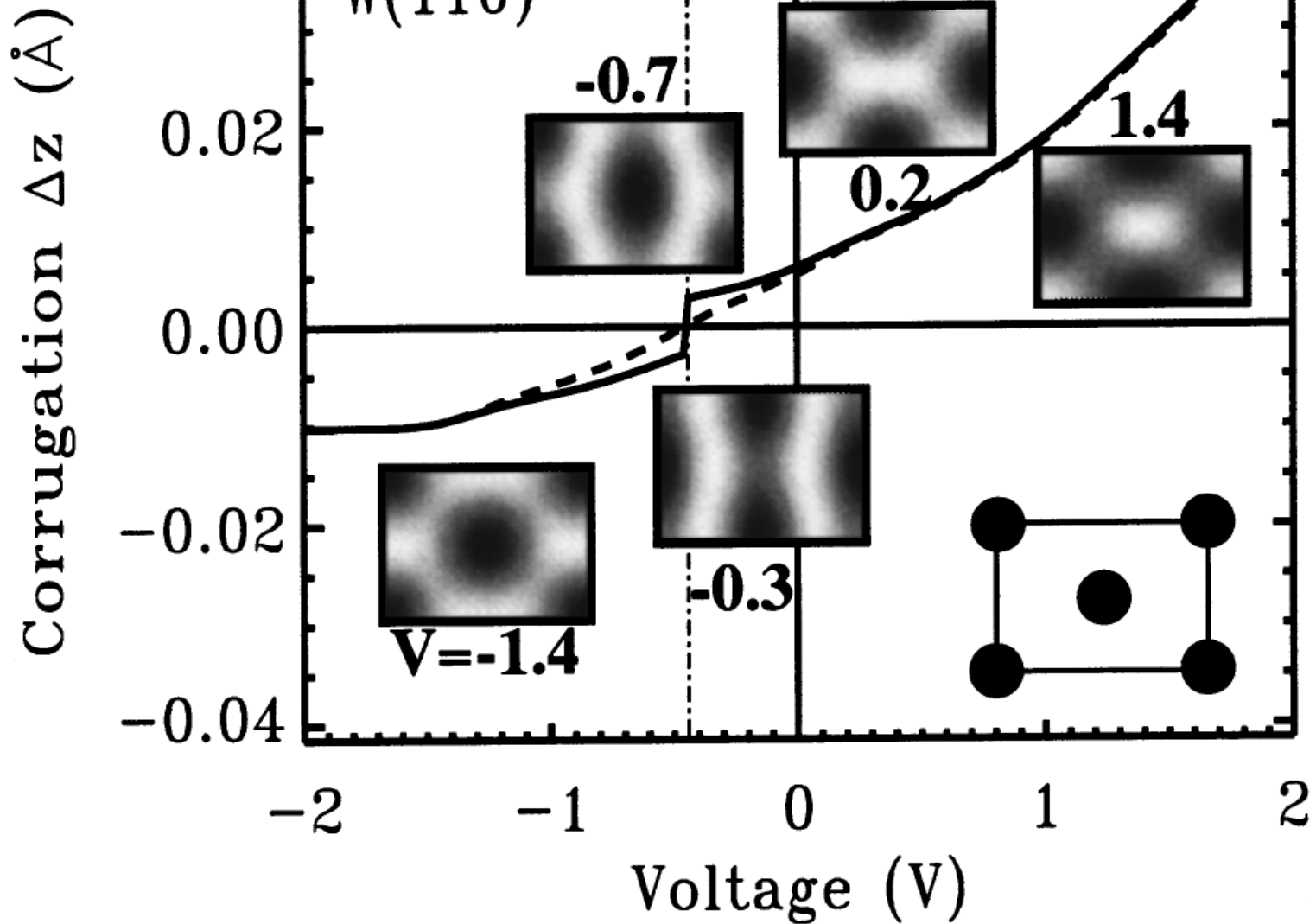
R. Pascal, M. Bode, and R. Wiesendanger

Zentrum für Mikrostrukturforschung, Universität Hamburg, D-20355 Hamburg, Germany

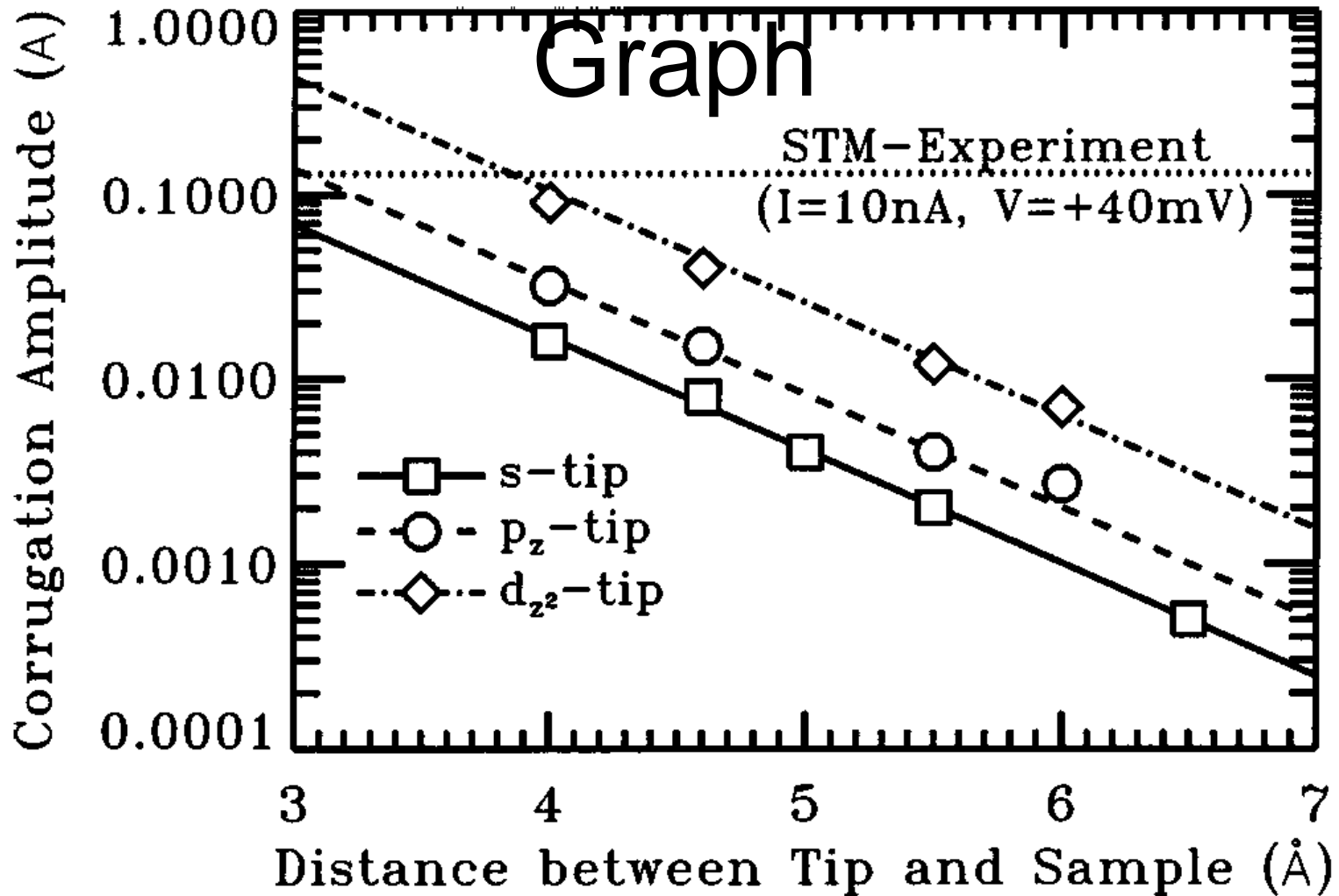
(Received 15 July 1998)



Configuration/Voltage Graph

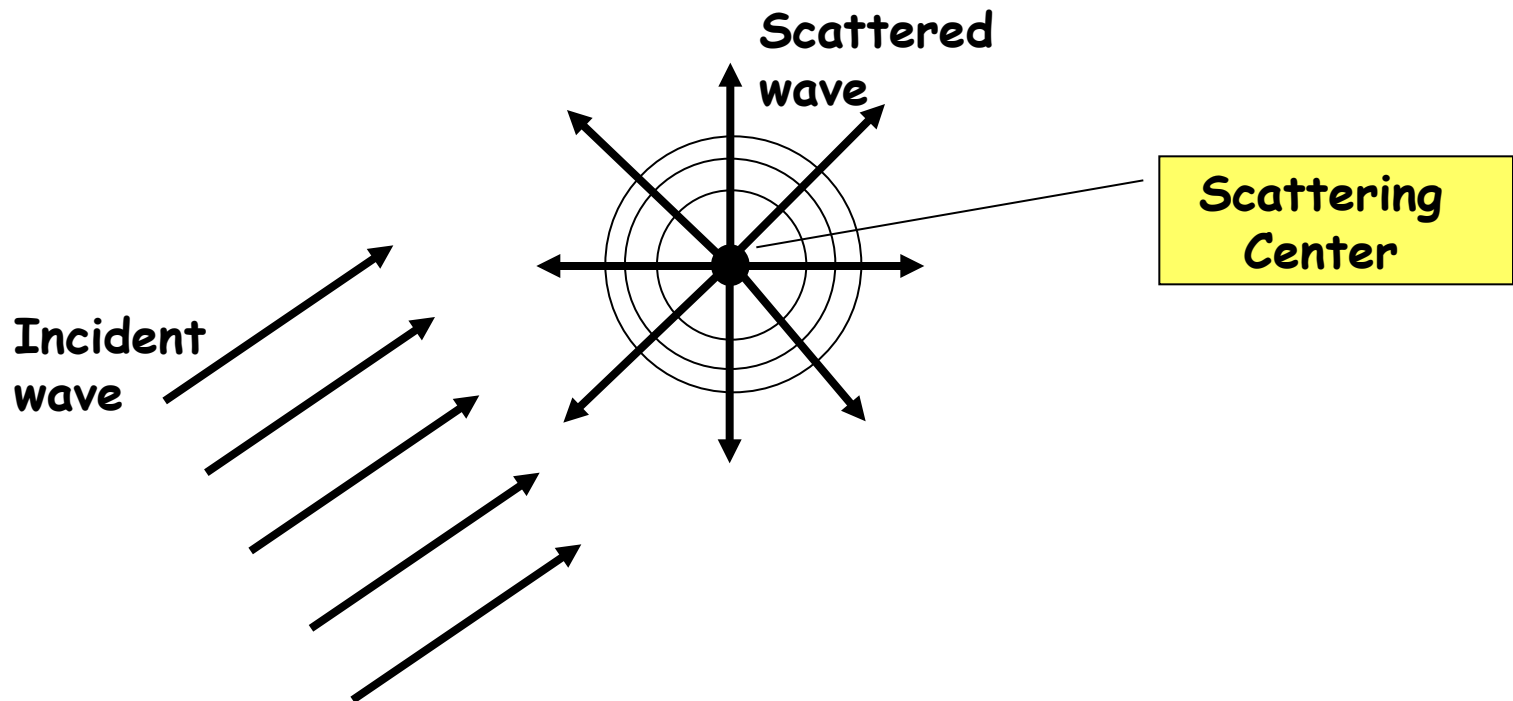


Corrugation Amplitude/Distance

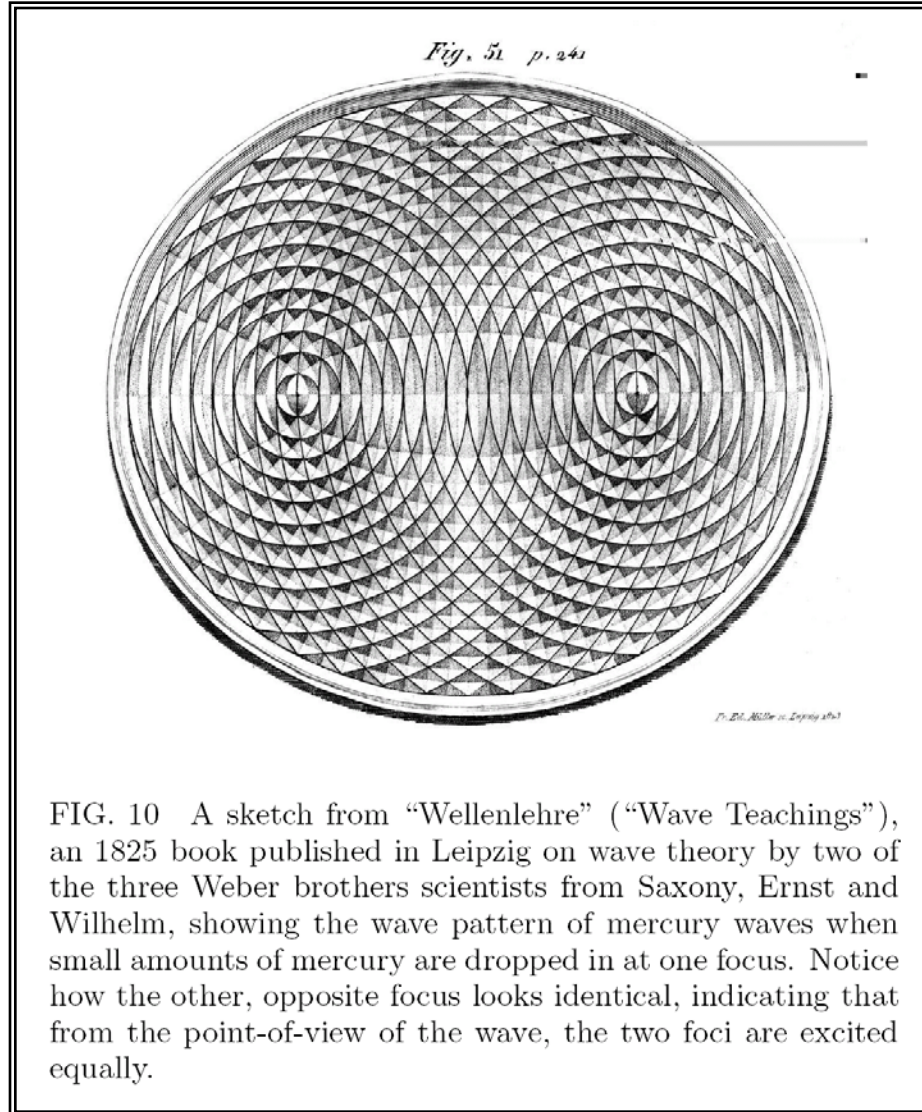


Quantum Corrals

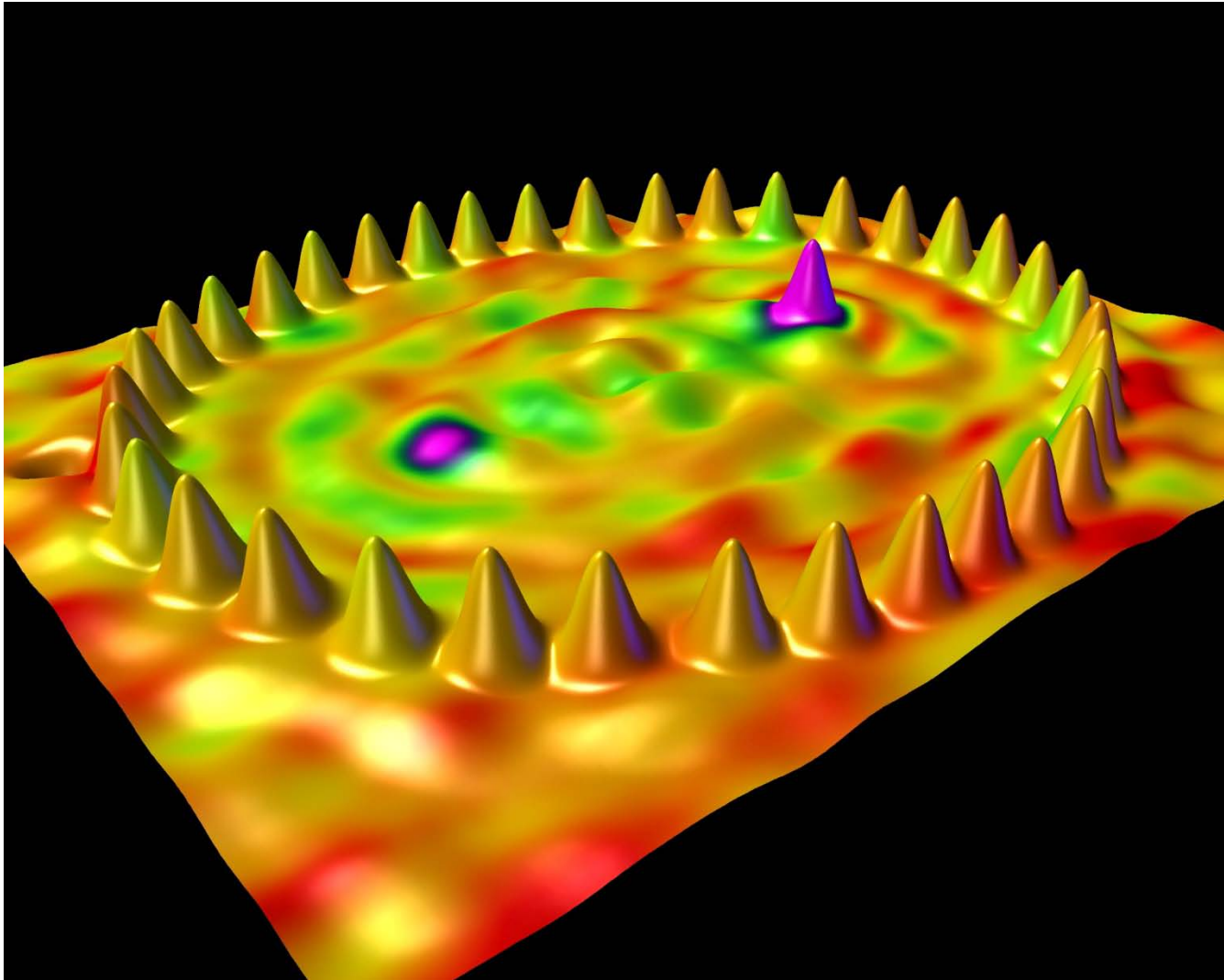
- Confine electrons inside artificial structures
- Requires atomically flat metallic substrates
- Requires the presence of surface electron states
- Construct 2D atomic "fence" of electron scattering centers
- New way of guiding information through a solid



Elliptical Shapes are Special



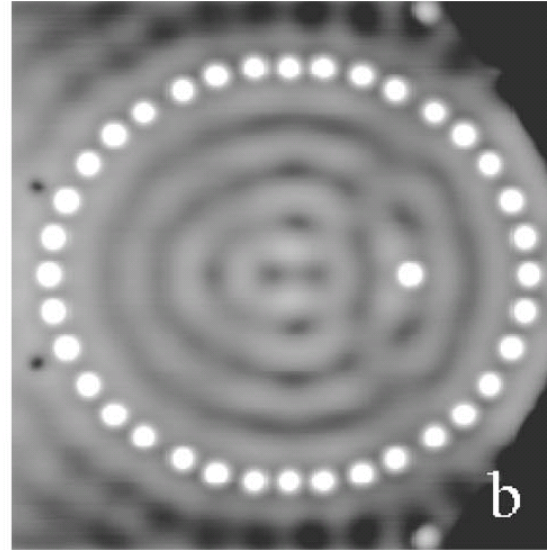
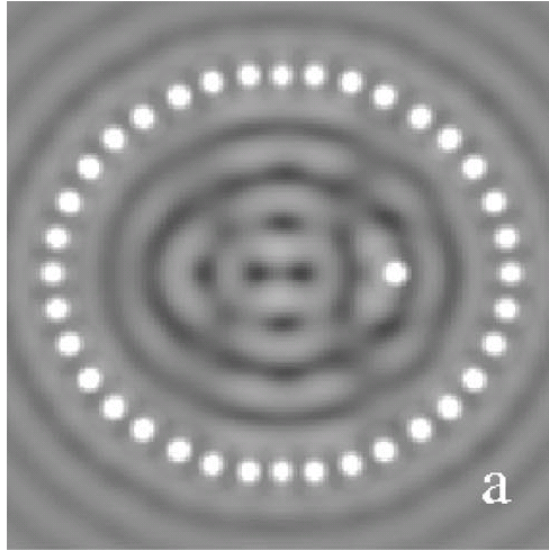
36 cobalt atoms forming an elliptical structure on Cu(111) substrate



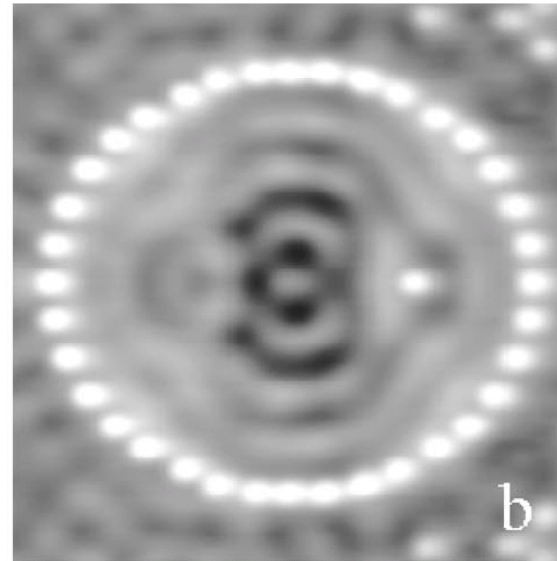
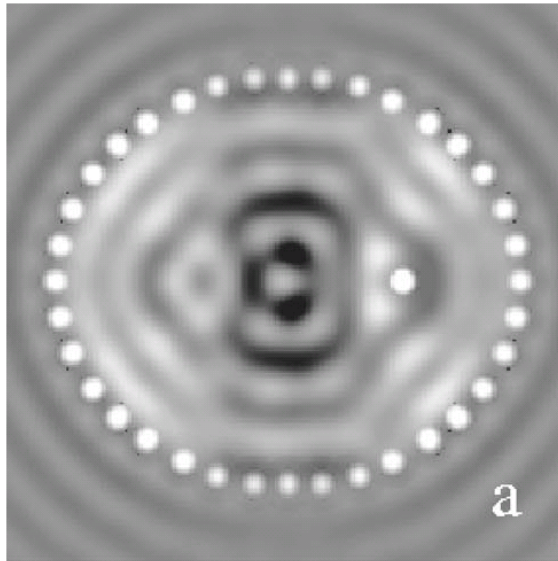
Theory

Experiment

Topography



DOS
(dI/dV)



Quantum Corral Simulation

<http://mw.concord.org/modeler1.3/mirror/quantum/corral.html>

See also Prof. E.J. Heller's lecture at
<https://nanohub.org/resources/3253/>

SUMMARY

To do STM well, you need

- i) high quality, FLAT, well characterized, electrically conducting substrates;
 - ii) UHV and Low Temperature equipment;
 - iii) lots of time and money;
 - iv) infrastructure, infrastructure, infrastructure;
- and**
- i) good theoretical support.